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forming a p transistor and an n transistor in the heterostructure, wherein the strained layer comprises a channel of at least one of the transistors, the transistors being interconnected in a CMOS circuit.

6 33. The method of claim 32 wherein the heterostructure further comprises an insulating layer below the strained layer.

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7 34. The method of claim 32 wherein the heterostructure further comprises a SiGe graded buffer layer positioned between the relaxed $Si_{1-x}Ge_x$ layer and the Si substrate.

8 35. The method of claim 32 wherein the strained layer comprises Si.

9 36. The method of claim 32 wherein $0.1 < x < 0.5$.

10 37. The method of claim 32 wherein the CMOS circuit comprises a logic gate.

11 38. The method of claim 37 wherein the logic gate is a NOR gate.

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